

Product Change Notification - CYER-09EMYS877

Date: 06 Feb 2014

Product Category: 8-bit Microcontrollers

Notification subject: CCB 1155.09 Final Notification: Qualification of selected products available in the 40L PDIP and 28L PDIP packages with palladium coated copper (PdCu) bond wire at MTAI assembly site.

Notification text: **PCN Status:**
Final notification

Microchip Parts Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

PCN_CYER-09EMYS877_Affected_CPN.xls

PCN_CYER-09EMYS877_Affected_CPN.pdf

Description of Change:

Qualification of selected products available in the 40L PDIP and 28L PDIP packages with palladium coated copper (PdCu) bond wire at MTAI assembly site.

NOTE: Selected products are non-automotive standalone analog and PIC MCU devices. Please review the affected CPN lists (attached) to identify the actual parts affected.

Pre Change:

Gold (Au) wire

Post Change:

Palladium coated copper (PdCu) bond wire

Impacts to Data Sheet:

None

Reason for Change:

To improve manufacturability

Change Implementation Status:

In progress

Estimated First Ship Dates:

PIC MCU Devices: October 18, 2013 (Date code: 1342)

Analog Devices: January 17, 2014 (Date code: 1403)

PIC16C55/57/71 Devices: February 28, 2014 (Date code 1409)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

August 23, 2013: Initial notification issue date.

September 5, 2013: Final notification issue date. Attached qualification report.

December 17, 2013: Revised PCN to include Analog devices.

Revised the affected parts list to include analog devices and included the estimated first ship date. Revised the estimated first ship date for analog devices only to 1/17/2014.

February 6, 2014: Revised PCN to include PIC16C55/57/71 devices. Revised the affected parts list to include PIC16C55/57/71 devices and included the estimated first ship date. Revised the estimated first ship date for PIC16C55/57/71 devices only to 2/28/2014.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_CYER-09EMYS877_Affected CPN.pdf](#) [PCN_CYER-09EMYS877_Qual Report.pdf](#) [PCN_CYER-09EMYS877_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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PCN_CYER-09EMYS877	
CATALOG_PART_NBR	Estimated First Ship Date
DSPIC30F3011-20E/P	10/18/2013
DSPIC30F3011-20I/P	10/18/2013
DSPIC30F3011-30I/P	10/18/2013
DSPIC30F3014-20E/P	10/18/2013
DSPIC30F3014-20I/P	10/18/2013
DSPIC30F3014-30I/P	10/18/2013
DSPIC30F4011-20E/P	10/18/2013
DSPIC30F4011-20I/P	10/18/2013
DSPIC30F4011-30I/P	10/18/2013
DSPIC30F4013-20E/P	10/18/2013
DSPIC30F4013-20I/P	10/18/2013
DSPIC30F4013-30I/P	10/18/2013
PIC16C64A-04/P	10/18/2013
PIC16C64A-04I/P	10/18/2013
PIC16C64A-04I/P053	10/18/2013
PIC16C64A-10/P	10/18/2013
PIC16C64A-20/P	10/18/2013
PIC16C64A-20I/P	10/18/2013
PIC16C65A-04/P	10/18/2013
PIC16C65A-10/P	10/18/2013
PIC16C65A-20/P	10/18/2013
PIC16C65A-20I/P	10/18/2013
PIC16C65B-04/P	10/18/2013
PIC16C65B-04I/P	10/18/2013
PIC16C65B-20/P	10/18/2013
PIC16C65B-20I/P	10/18/2013
PIC16C662-04I/P	10/18/2013
PIC16C67-04/P	10/18/2013
PIC16C67-04I/P	10/18/2013
PIC16C67-10/P	10/18/2013
PIC16C67-20/P	10/18/2013
PIC16C67-20I/P	10/18/2013
PIC16C74A-04/P	10/18/2013
PIC16C74A-04I/P	10/18/2013
PIC16C74A-10/P	10/18/2013
PIC16C74A-10I/P	10/18/2013
PIC16C74A-20/P	10/18/2013
PIC16C74A-20E/P	10/18/2013
PIC16C74A-20I/P	10/18/2013
PIC16C74B-04/P	10/18/2013
PIC16C74B-04I/P	10/18/2013
PIC16C74B-04I/P4AP	10/18/2013
PIC16C74B-20/P	10/18/2013
PIC16C74B-20E/P	10/18/2013
PIC16C74B-20I/P	10/18/2013

PIC16C765-I/P	10/18/2013
PIC16C77-04/P	10/18/2013
PIC16C77-04E/P	10/18/2013
PIC16C77-04I/P	10/18/2013
PIC16C77-10/P	10/18/2013
PIC16C77-10I/P	10/18/2013
PIC16C77-20/P	10/18/2013
PIC16C77-20E/P	10/18/2013
PIC16C77-20I/P	10/18/2013
PIC16C774/P	10/18/2013
PIC16C774-E/P	10/18/2013
PIC16C774-I/P	10/18/2013
PIC16F59-E/P	10/18/2013
PIC16F59-I/P	10/18/2013
PIC16F747-I/P	10/18/2013
PIC16F74-E/P	10/18/2013
PIC16F74-I/P	10/18/2013
PIC16F74-I/P4AP	10/18/2013
PIC16F777-E/P	10/18/2013
PIC16F777-I/P	10/18/2013
PIC16F77-E/P	10/18/2013
PIC16F77-I/P	10/18/2013
PIC16F77-I/P4AP	10/18/2013
PIC16F871-E/P	10/18/2013
PIC16F871-I/P	10/18/2013
PIC16F874-04/P	10/18/2013
PIC16F874-04I/P	10/18/2013
PIC16F874-20/P	10/18/2013
PIC16F874-20I/P	10/18/2013
PIC16F874A-E/P	10/18/2013
PIC16F874A-I/P	10/18/2013
PIC16F877-04/P	10/18/2013
PIC16F877-04E/P	10/18/2013
PIC16F877-04I/P	10/18/2013
PIC16F877-10E/P	10/18/2013
PIC16F877-20/P	10/18/2013
PIC16F877-20I/P	10/18/2013
PIC16F877A-E/P	10/18/2013
PIC16F877A-I/P	10/18/2013
PIC16F884-E/P	10/18/2013
PIC16F884-I/P	10/18/2013
PIC16F887-E/P	10/18/2013
PIC16F887-I/P	10/18/2013
PIC16F914-E/P	10/18/2013
PIC16F914-I/P	10/18/2013
PIC16F917-E/P	10/18/2013
PIC16F917-I/P	10/18/2013

PIC16LC64A-04/P	10/18/2013
PIC16LC64A-04I/P	10/18/2013
PIC16LC65A-04/P	10/18/2013
PIC16LC65B-04/P	10/18/2013
PIC16LC65B-04I/P	10/18/2013
PIC16LC67-04/P	10/18/2013
PIC16LC74A-04/P	10/18/2013
PIC16LC74B-04/P	10/18/2013
PIC16LC74B-04I/P	10/18/2013
PIC16LC774/P	10/18/2013
PIC16LF747-I/P	10/18/2013
PIC16LF74-I/P	10/18/2013
PIC16LF777-I/P	10/18/2013
PIC16LF77-I/P	10/18/2013
PIC16LF871-I/P	10/18/2013
PIC16LF874-04/P	10/18/2013
PIC16LF874-04I/P	10/18/2013
PIC16LF874A-I/P	10/18/2013
PIC16LF877-04/P	10/18/2013
PIC16LF877-04I/P	10/18/2013
PIC16LF877A-I/P	10/18/2013
PIC17C42A-16/P	10/18/2013
PIC17C42A-16I/P	10/18/2013
PIC17C42A-25/P	10/18/2013
PIC17C42A-33/P	10/18/2013
PIC17C42A-33I/P	10/18/2013
PIC17C43-16/P	10/18/2013
PIC17C43-16I/P	10/18/2013
PIC17C43-25/P	10/18/2013
PIC17C43-33/P	10/18/2013
PIC17C43-33I/P	10/18/2013
PIC17C44-16/P	10/18/2013
PIC17C44-16I/P	10/18/2013
PIC17C44-25/P	10/18/2013
PIC17C44-25E/P	10/18/2013
PIC17C44-25I/P	10/18/2013
PIC17C44-33/P	10/18/2013
PIC17C44-33I/P	10/18/2013
PIC17LC44-08I/P	10/18/2013
PIC18C442-I/P	10/18/2013
PIC18C452-E/P	10/18/2013
PIC18C452-I/P	10/18/2013
PIC18F4220-E/P	10/18/2013
PIC18F4220-I/P	10/18/2013
PIC18F4221-E/P	10/18/2013
PIC18F4221-I/P	10/18/2013
PIC18F4320-E/P	10/18/2013

PIC18F4320-I/P	10/18/2013
PIC18F4320-I/PC05	10/18/2013
PIC18F4321-E/P	10/18/2013
PIC18F4321-I/P	10/18/2013
PIC18F4331-E/P	10/18/2013
PIC18F4331-I/P	10/18/2013
PIC18F4410-E/P	10/18/2013
PIC18F4410-I/P	10/18/2013
PIC18F4420-E/P	10/18/2013
PIC18F4420-I/P	10/18/2013
PIC18F4423-E/P	10/18/2013
PIC18F4423-I/P	10/18/2013
PIC18F442-E/P	10/18/2013
PIC18F442-I/P	10/18/2013
PIC18F4431-E/P	10/18/2013
PIC18F4431-I/P	10/18/2013
PIC18F4439-I/P	10/18/2013
PIC18F4450-I/P	10/18/2013
PIC18F4455-I/P	10/18/2013
PIC18F4455-I/PC03	10/18/2013
PIC18F4458-I/P	10/18/2013
PIC18F4480-E/P	10/18/2013
PIC18F4480-I/P	10/18/2013
PIC18F448-I/P	10/18/2013
PIC18F44J10-I/P	10/18/2013
PIC18F4510-E/P	10/18/2013
PIC18F4510-I/P	10/18/2013
PIC18F4515-E/P	10/18/2013
PIC18F4515-I/P	10/18/2013
PIC18F4520-E/P	10/18/2013
PIC18F4520-I/P	10/18/2013
PIC18F4523-E/P	10/18/2013
PIC18F4523-I/P	10/18/2013
PIC18F4525-E/P	10/18/2013
PIC18F4525-I/P	10/18/2013
PIC18F452-E/P	10/18/2013
PIC18F452-I/P	10/18/2013
PIC18F452-I/P039	10/18/2013
PIC18F4539-I/P	10/18/2013
PIC18F4550-I/P	10/18/2013
PIC18F4553-I/P	10/18/2013
PIC18F4580-E/P	10/18/2013
PIC18F4580-I/P	10/18/2013
PIC18F4585-E/P	10/18/2013
PIC18F4585-H/P	10/18/2013
PIC18F4585-I/P	10/18/2013
PIC18F458-E/P	10/18/2013

PIC18F458-I/P	10/18/2013
PIC18F45J10-I/P	10/18/2013
PIC18F4610-E/P	10/18/2013
PIC18F4610-I/P	10/18/2013
PIC18F4620-E/P	10/18/2013
PIC18F4620-I/P	10/18/2013
PIC18F4680-E/P	10/18/2013
PIC18F4680-H/P	10/18/2013
PIC18F4680-I/P	10/18/2013
PIC18F4682-E/P	10/18/2013
PIC18F4682-I/P	10/18/2013
PIC18F4685-E/P	10/18/2013
PIC18F4685-I/P	10/18/2013
PIC18F46J11-I/PAQL	10/18/2013
PIC18F46J50-I/PAQL	10/18/2013
PIC18LC452-I/P	10/18/2013
PIC18LF4220-I/P	10/18/2013
PIC18LF4221-I/P	10/18/2013
PIC18LF4320-I/P	10/18/2013
PIC18LF4321-I/P	10/18/2013
PIC18LF4331-I/P	10/18/2013
PIC18LF4410-I/P	10/18/2013
PIC18LF4420-I/P	10/18/2013
PIC18LF4423-I/P	10/18/2013
PIC18LF442-I/P	10/18/2013
PIC18LF4431-I/P	10/18/2013
PIC18LF4450-I/P	10/18/2013
PIC18LF4455-I/P	10/18/2013
PIC18LF4458-I/P	10/18/2013
PIC18LF4480-I/P	10/18/2013
PIC18LF448-I/P	10/18/2013
PIC18LF44J10-I/P	10/18/2013
PIC18LF4510-I/P	10/18/2013
PIC18LF4515-I/P	10/18/2013
PIC18LF4520-I/P	10/18/2013
PIC18LF4523-I/P	10/18/2013
PIC18LF4525-I/P	10/18/2013
PIC18LF452-I/P	10/18/2013
PIC18LF4539-I/P	10/18/2013
PIC18LF4550-I/P	10/18/2013
PIC18LF4553-I/P	10/18/2013
PIC18LF4580-I/P	10/18/2013
PIC18LF4585-I/P	10/18/2013
PIC18LF458-I/P	10/18/2013
PIC18LF45J10-I/P	10/18/2013
PIC18LF4610-I/P	10/18/2013
PIC18LF4620-I/P	10/18/2013

PIC18LF4680-I/P	10/18/2013
PIC18LF4682-I/P	10/18/2013
PIC18LF4685-I/P	10/18/2013
PIC18LF46J50-I/PAQQ	10/18/2013
CF775-04/P	10/18/2013
PIC16C557-I/P	10/18/2013
PIC16C55A-04/P	10/18/2013
PIC16C55A-04I/P	10/18/2013
PIC16C55A-20/P	10/18/2013
PIC16C55A-20I/P	10/18/2013
PIC16C55A-40/P	10/18/2013
PIC16C57C-04/P	10/18/2013
PIC16C57C-04/P072	10/18/2013
PIC16C57C-04/P073	10/18/2013
PIC16C57C-04E/P	10/18/2013
PIC16C57C-04I/P	10/18/2013
PIC16C57C-04I/P027	10/18/2013
PIC16C57C-04I/P063	10/18/2013
PIC16C57C-04I/P069	10/18/2013
PIC16C57C-04I/P071	10/18/2013
PIC16C57C-04I/P077	10/18/2013
PIC16C57C-20/P	10/18/2013
PIC16C57C-20I/P	10/18/2013
PIC16C57C-40/P	10/18/2013
PIC16C622-ME	10/18/2013
PIC16C711-ME/P	10/18/2013
PIC16C715-ME/P	10/18/2013
PIC16F57-E/P	10/18/2013
PIC16F57-E/PG	10/18/2013
PIC16F57-I/P	10/18/2013
PIC16F57-I/P022	10/18/2013
PIC16F57-I/P032	10/18/2013
PIC16F57-I/P033	10/18/2013
PIC16F57-I/P034	10/18/2013
PIC16F57-I/P037	10/18/2013
PIC16F57-I/P038	10/18/2013
PIC16F57-I/PC02	10/18/2013
PIC16F57-I/PG	10/18/2013
PIC16LC55A-04/P	10/18/2013
PIC16LC55A-04I/P	10/18/2013
PIC16LC57C-04/P	10/18/2013
PIC16LC57C-04I/P	10/18/2013
TC7106ACPL	1/17/2014
TC7106AIPL	1/17/2014
TC7106CPL	1/17/2014
TC7106IPL	1/17/2014
TC7107ACPL	1/17/2014

TC7107AIPL	1/17/2014
TC7107CPL	1/17/2014
TC7107IPL	1/17/2014
TC7109ACPL	1/17/2014
TC7109ACPL514	1/17/2014
TC7109CPL	1/17/2014
TC7116ACPL	1/17/2014
TC7116CPL	1/17/2014
TC7117ACPL	1/17/2014
TC7117CPL	1/17/2014
TC7126ACPL	1/17/2014
TC7126CPL	1/17/2014
TC7126IPL	1/17/2014
TC7129CPL	1/17/2014
TC850CPL	1/17/2014
TC7135CPI	1/17/2014
TC835CPI	1/17/2014
PIC16C55-10/P	2/28/2014
PIC16C55-10I/P	2/28/2014
PIC16C55-HS/P	2/28/2014
PIC16C55-HSI/P	2/28/2014
PIC16C55-LP/P	2/28/2014
PIC16C55-LPI/P	2/28/2014
PIC16C55-RC/P	2/28/2014
PIC16C55-RCI/P	2/28/2014
PIC16C55-XT/P	2/28/2014
PIC16C55-XTI/P	2/28/2014
PIC16C57-10/P	2/28/2014
PIC16C57-10I/P	2/28/2014
PIC16C57-HS/P	2/28/2014
PIC16C57-HSE/P	2/28/2014
PIC16C57-HSI/P	2/28/2014
PIC16C57-LP/P	2/28/2014
PIC16C57-LPI/P	2/28/2014
PIC16C57-RC/P	2/28/2014
PIC16C57-RCE/P	2/28/2014
PIC16C57-RCI/P	2/28/2014
PIC16C57-RCI/P175	2/28/2014
PIC16C57-XT/P	2/28/2014
PIC16C57-XTE/P	2/28/2014
PIC16C57-XTI/P	2/28/2014
PIC16C71-ME/P	2/28/2014



QUALIFICATION REPORT RELIABILITY LABORATORY

PCN #: CYER-09EMYS877

Date
August 21, 2013

Qualification of selected products available in the 40L PDIP package with palladium coated copper (PdCu) bond wire at MTAI assembly site. The 28L PDIP package will qualify at MTAI assembly site by similarity.

Distribution

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MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose	Qualification of selected products available in the 40L PDIP package with palladium coated copper (PdCu) bond wire at MTAI assembly site. The 28L PDIP package will qualify at MTAI assembly site by similarity.
CN	BC130711
QUAL ID	Q13077
Part No.	PIC18F448-I/PREL
MP CODE	C5AL27S2XREL
Bonding No.	A-033982 Rev. F
CCB No.	1155.09
<u>Package</u>	
Type	40L PDIP
Package size	600 mils
Die thickness	15 mils
Die size	152.70 x 243.60 mils
<u>Lead Frame</u>	
Paddle size	300 x 300 mils
Material	CDA194
Surface	Ag spot
Process	Stamp
Lead Lock	Yes
Part Number	10104009
<u>Die attach material</u>	
Epoxy	CRM-1064L
Wire	PdCu wire
Mold Compound	GE800
Plating Composition	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI140902458	TMPE213309872.330	13224G1
MTAI140902459	TMPE213309872.320	13224G2
MTAI140902460	TMPE213309872.310	13224G3

Result

Pass Fail _____

40L PDIP (.600") assembled by MTAI pass reliability test per QCI-39000.

Prepared By: _____ **Date:** August 21, 2013 **(Reliability Engineer)**

(Mr.Thinnapol Nakkasun)

Approved By: _____ **Date:** August 21, 2013 **(Reliability Manager)**

(Mr. Somnuek Thongprasert)

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Electrical Test	Electrical Test: +25°C and 85°C System: J750	JESD22- A113	693(0)	693		Good Devices
Temp Cycle	Stress Condition: (Standard) -65°C to +150°C, 50, 250, 500 Cycles System : TABAI ESPEC TSA-70H Electrical Test: + 85°C System: J750	JESD22- A104	231(0)	0/231	Pass	
UNBIASED-HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: J750	JESD22- A118	231(0)	0/231	Pass	
HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: J750	JESD22- A110	231(0)	0/231	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB	JESD22- A103		45		45 units
	Electrical Test: +25°C and 85°C System: J750		45(0)	0/45	Pass	
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	JESD22- B116	30 (0) Wires	0/30	Pass	
	Bond Shear (15.00 grams)		30 (0) bonds	0/30	Pass	